

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 19 February 2026, 14:37 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.63%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	9.75%	Carbon black	1333-86-4	1%
			Phenol, polymer with 1,4-bis(methoxymethyl)benzene	26834-02-6	10%
			Magnesium hydroxide (Mg(OH) ₂)	1309-42-8	14%
			4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6	15%
			Silicon dioxide	60676-86-0	60%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.005%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.75%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	88.865%	Elemental zinc	7440-66-6	0.52%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	0.7%
			Tin elemental	7440-31-5	1%
			COPPER, ELEMENTAL	7440-50-8	97.78%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-323F_(AO)_Pb&H-free	Diode SMD	0.0033	g

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